

General Description

AO4630 uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. This complementary N and P channel MOSFET configuration is ideal for low Input Voltage inverter applications.

Product Summary

N-Channel

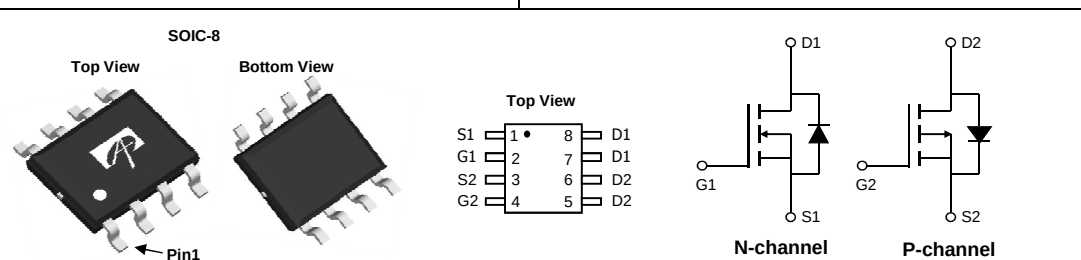
$V_{DS} = 30V$
 $I_D = 7A$ ($V_{GS} = 10V$)
 $R_{DS(ON)}$
 $< 23m\Omega$ ($V_{GS} = 10V$)
 $< 28m\Omega$ ($V_{GS} = 4.5V$)
 $< 36m\Omega$ ($V_{GS} = 2.5V$)

P-Channel

$-30V$
 $-5A$ ($V_{GS} = -10V$)
 $R_{DS(ON)}$
 $< 48m\Omega$ ($V_{GS} = -10V$)
 $< 57m\Omega$ ($V_{GS} = -4.5V$)
 $< 78m\Omega$ ($V_{GS} = -2.5V$)

100% UIS Tested
 100% R_g Tested

100% UIS Tested
 100% R_g Tested



Orderable Part Number		Package Type	Form	Minimum Order Quantity	
AO4630		SO-8	Tape & Reel	3000	
Absolute Maximum Ratings T _A =25°C unless otherwise noted					
Parameter		Symbol	Max N-channel	Max P-channel	Units
Drain-Source Voltage		V _{DS}	30	-30	V
Gate-Source Voltage		V _{GS}	±12	±12	V
Continuous Drain Current	T _A =25°C	I _D	7	-5	A
	T _A =70°C		5.6	-4	
Pulsed Drain Current ^C		I _{DM}	30	-25	
Avalanche Current ^C		I _{AS}	14	18	A
Avalanche energy L=0.1mH ^C		E _{AS}	10	16	mJ
V _{DS} Spike	10μs	V _{SPIKE}	36	-36	V
Power Dissipation ^B	T _A =25°C	P _D	2		W
	T _A =70°C		1.3		
Junction and Storage Temperature Range		T _J , T _{STG}	-55 to 150		°C

Thermal Characteristics					
Parameter	Symbol	Typ	Max	Units	
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	48	62.5	$^\circ C/W$	
Maximum Junction-to-Ambient ^{A,D}		74	90		
Maximum Junction-to-Lead	$R_{\theta JL}$	32	40	$^\circ C/W$	

N-Channel Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0V	30			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =30V, V _{GS} =0V T _J =55°C			1 5	μA
I _{GSS}	Gate-Body leakage current	V _{DS} =0V, V _{GS} =±12V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	0.65	1.05	1.45	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =7A T _J =125°C		17.8 28	23 40	mΩ
		V _{GS} =4.5V, I _D =6A		19	28	mΩ
		V _{GS} =2.5V, I _D =5A		24	36	mΩ
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =7A		35		S
V _{SD}	Diode Forward Voltage	I _S =1A, V _{GS} =0V		0.7	1	V
I _S	Maximum Body-Diode Continuous Current				2.5	A
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =15V, f=1MHz		670		pF
C _{oss}	Output Capacitance			75		pF
C _{rss}	Reverse Transfer Capacitance			45		pF
R _g	Gate resistance	f=1MHz	1.5	3	4.5	Ω
SWITCHING PARAMETERS						
Q _{g(10V)}	Total Gate Charge	V _{GS} =10V, V _{DS} =15V, I _D =7A		13	20	nC
Q _{g(4.5V)}	Total Gate Charge			6	12	nC
Q _{gs}	Gate Source Charge			1.3		nC
Q _{gd}	Gate Drain Charge			1.8		nC
t _{D(on)}	Turn-On DelayTime	V _{GS} =10V, V _{DS} =15V, R _L =2.2Ω, R _{GEN} =3Ω		3		ns
t _r	Turn-On Rise Time			2.5		ns
t _{D(off)}	Turn-Off DelayTime			25		ns
t _f	Turn-Off Fall Time			4		ns
t _{rr}	Body Diode Reverse Recovery Time	I _F =7A, di/dt=500A/μs		6.5		ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =7A, di/dt=500A/μs		7.5		nC

- A. The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A =25° C. The value in any given application depends on the user's specific board design.
- B. The power dissipation P_D is based on T_{J(MAX)}=150° C, using ≤ 10s junction-to-ambient thermal resistance.
- C. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150° C. Ratings are based on low frequency and duty cycles to keep initial T_J=25° C.
- D. The R_{θJA} is the sum of the thermal impedance from junction to lead R_{θJL} and lead to ambient.
- E. The static characteristics in Figures 1 to 6 are obtained using <300μs pulses, duty cycle 0.5% max.
- F. These curves are based on the junction-to-ambient thermal impedance which is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, assuming a maximum junction temperature of T_{J(MAX)}=150° C. The SOA curve provides a single pulse rating.

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N-Channel: TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

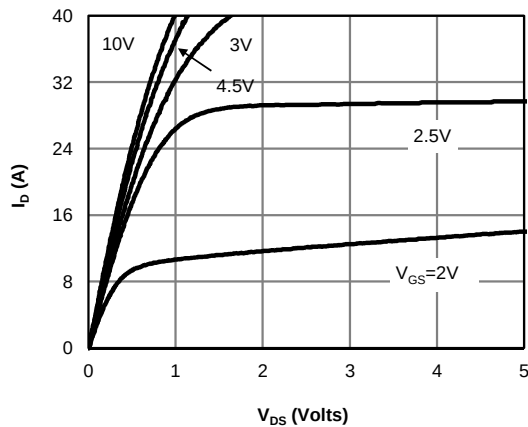


Figure 1: On-Region Characteristics (Note E)

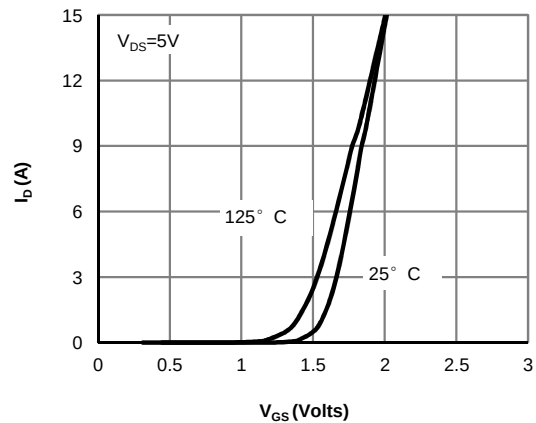


Figure 2: Transfer Characteristics (Note E)

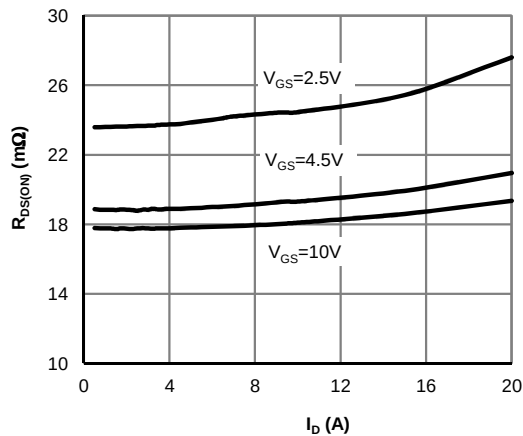


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

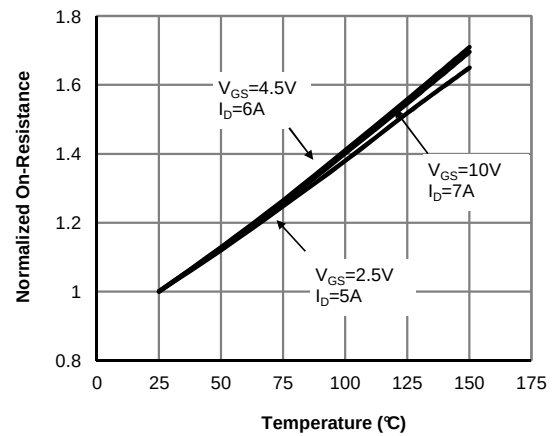


Figure 4: On-Resistance vs. Junction Temperature (Note E)

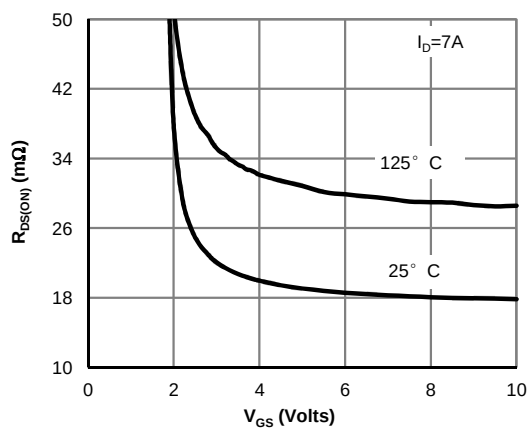


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

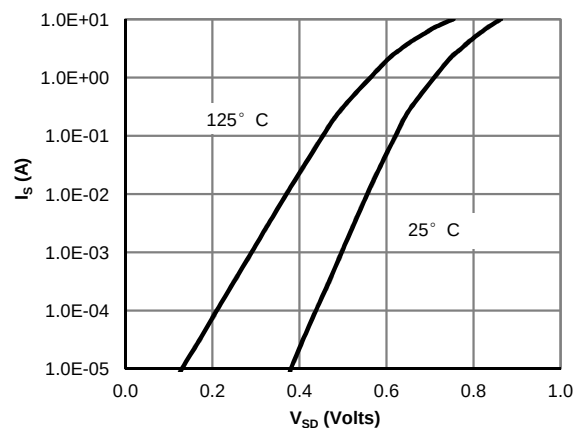


Figure 6: Body-Diode Characteristics (Note E)

N-Channel: TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

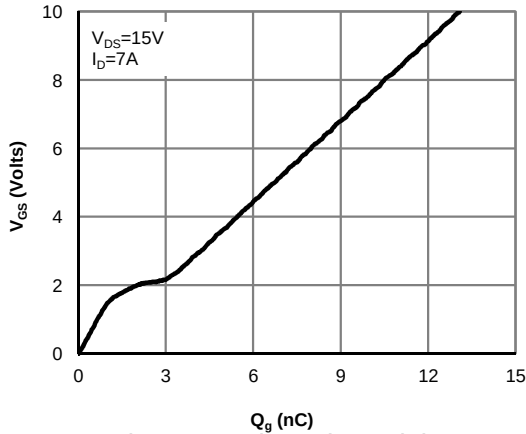


Figure 7: Gate-Charge Characteristics

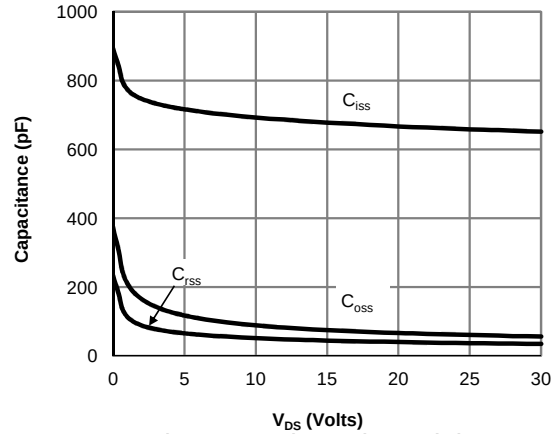


Figure 8: Capacitance Characteristics

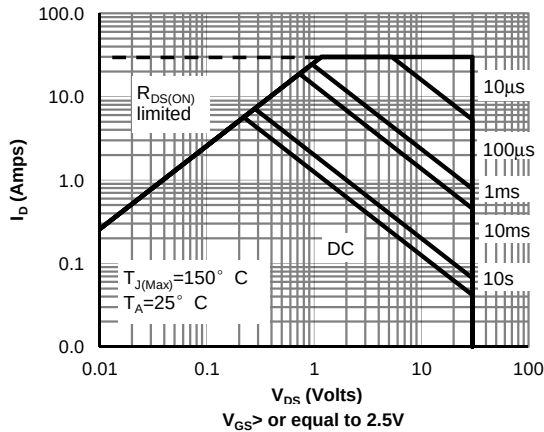


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

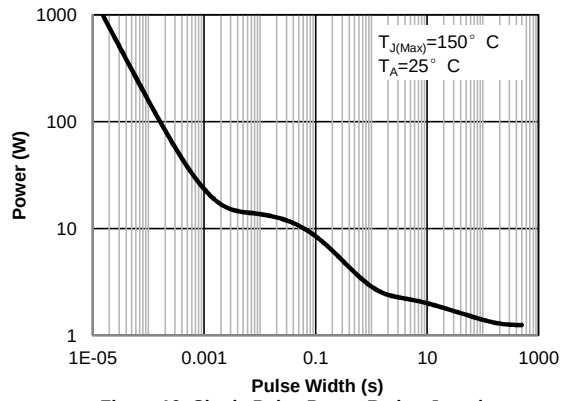


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note F)

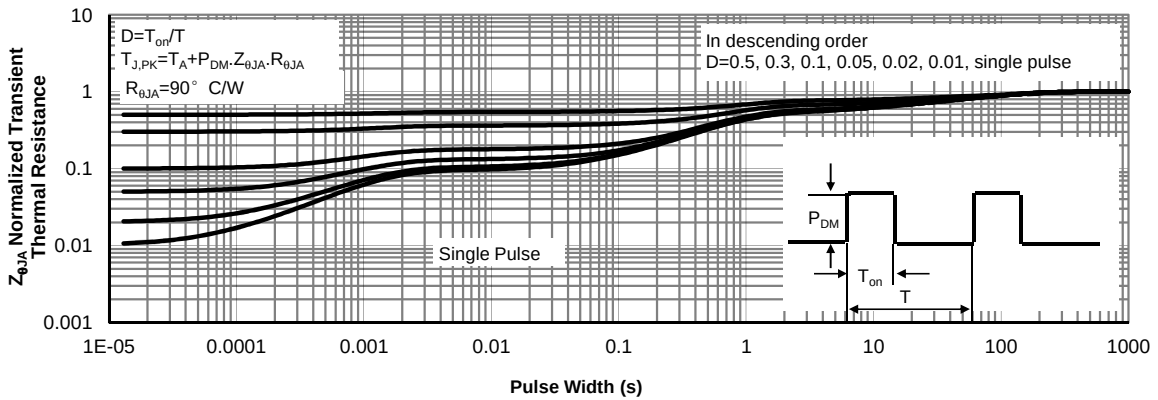


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

Figure A: Gate Charge Test Circuit & Waveforms

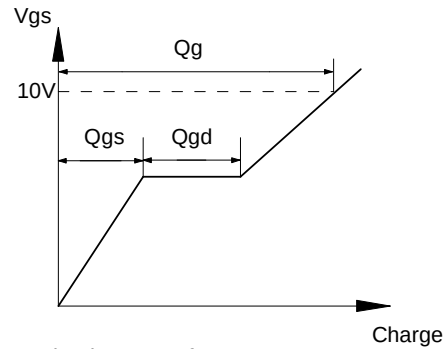
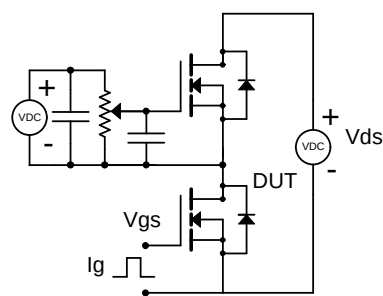


Figure B: Resistive Switching Test Circuit & Waveforms

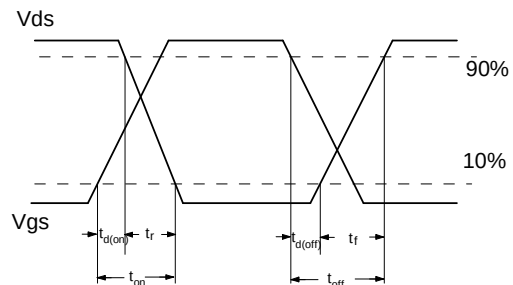
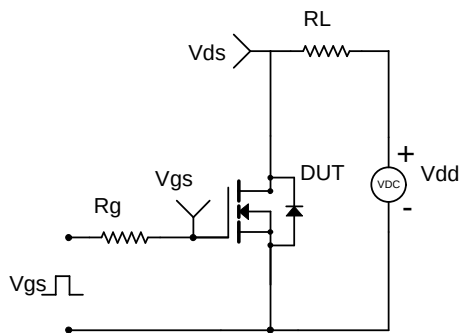


Figure C: Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

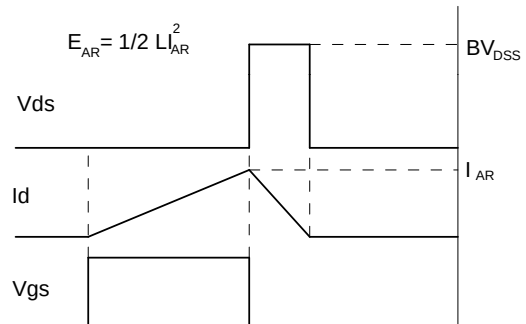
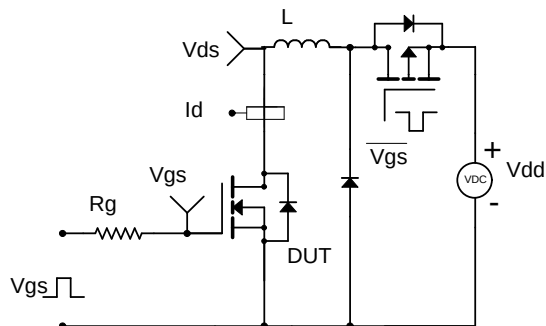
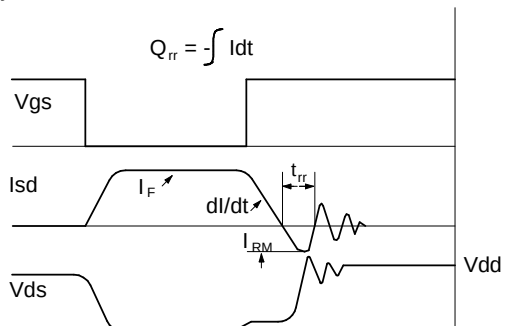
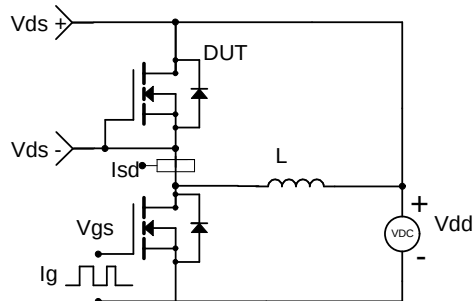


Figure D: Diode Recovery Test Circuit & Waveforms



P-Channel Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =-250μA, V _{GS} =0V	-30			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-30V, V _{GS} =0V T _J =55°C			-1 -5	μA
I _{GSS}	Gate-Body leakage current	V _{DS} =0V, V _{GS} =±12V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA	-0.5	-0.9	-1.3	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} =-10V, I _D =-5A T _J =125°C		40 48	48 60	mΩ
		V _{GS} =-4.5V, I _D =-3.5A		45	57	mΩ
		V _{GS} =-2.5V, I _D =-2.5A		60	78	mΩ
g _{FS}	Forward Transconductance	V _{DS} =-5V, I _D =-5A		18		S
V _{SD}	Diode Forward Voltage	I _S =-1A, V _{GS} =0V		-0.7	-1	V
I _S	Maximum Body-Diode Continuous Current				-2.5	A
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =-15V, f=1MHz		700		pF
C _{oss}	Output Capacitance			80		pF
C _{rss}	Reverse Transfer Capacitance			60		pF
R _g	Gate resistance	f=1MHz	4	8	12	Ω
SWITCHING PARAMETERS						
Q _{g(10V)}	Total Gate Charge	V _{GS} =-10V, V _{DS} =-15V, I _D =-5A		14	25	nC
Q _{g(4.5V)}	Total Gate Charge			7	15	nC
Q _{gs}	Gate Source Charge			1.5		nC
Q _{gd}	Gate Drain Charge			2.5		nC
t _{D(on)}	Turn-On DelayTime	V _{GS} =-10V, V _{DS} =-15V, R _L =3Ω, R _{GEN} =3Ω		6.5		ns
t _r	Turn-On Rise Time			3.5		ns
t _{D(off)}	Turn-Off DelayTime			41		ns
t _f	Turn-Off Fall Time			9		ns
t _{rr}	Body Diode Reverse Recovery Time	I _F =-5A, di/dt=500A/μs		15		ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =-5A, di/dt=500A/μs		40		nC

- A. The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C. The value in any given application depends on the user's specific board design.
- B. The power dissipation P_D is based on T_{J(MAX)}=150° C, using ≤ 10s junction-to-ambient thermal resistance.
- C. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150° C. Ratings are based on low frequency and duty cycles to keep initial T_J=25° C.
- D. The R_{θJA} is the sum of the thermal impedance from junction to lead R_{θJL} and lead to ambient.
- E. The static characteristics in Figures 1 to 6 are obtained using <300μs pulses, duty cycle 0.5% max.
- F. These curves are based on the junction-to-ambient thermal impedance which is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, assuming a maximum junction temperature of T_{J(MAX)}=150° C. The SOA curve provides a single pulse rating.

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P-Channel: TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

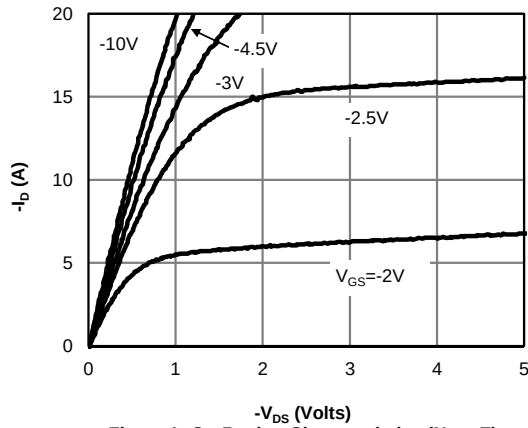


Figure 1: On-Region Characteristics (Note E)

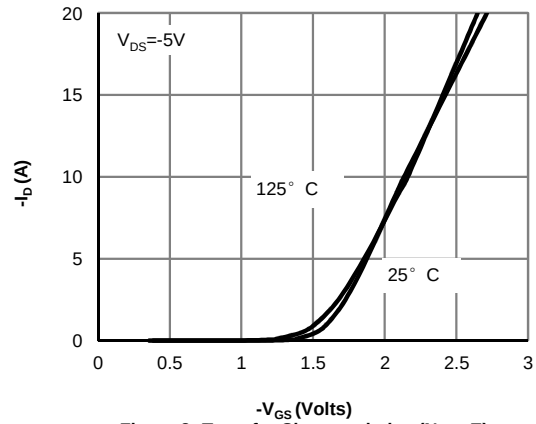


Figure 2: Transfer Characteristics (Note E)

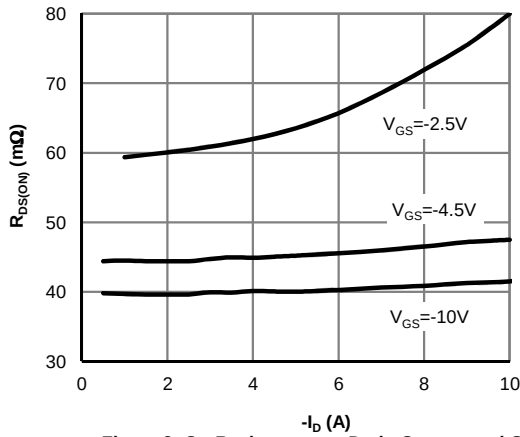


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

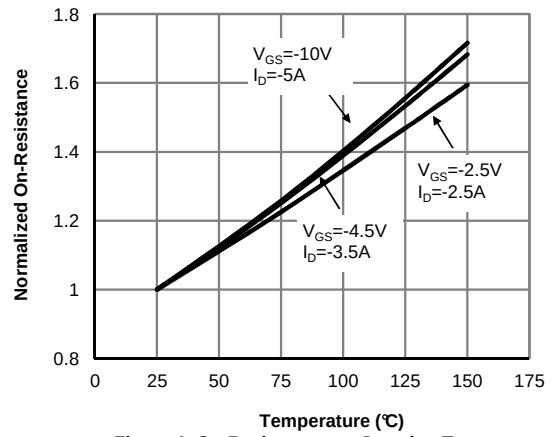


Figure 4: On-Resistance vs. Junction Temperature (Note E)

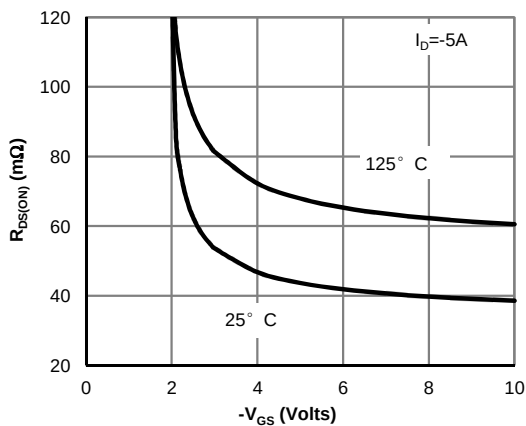


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

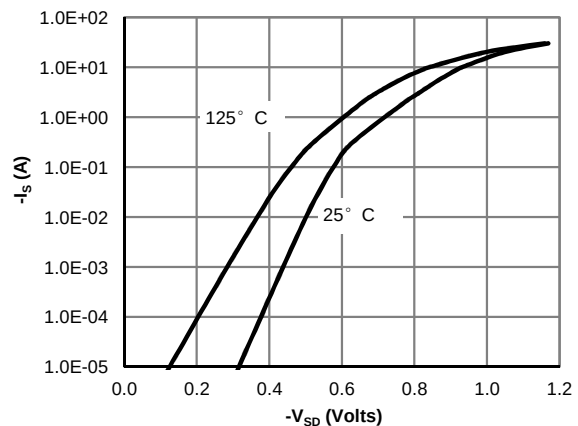


Figure 6: Body-Diode Characteristics (Note E)

P-Channel: TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

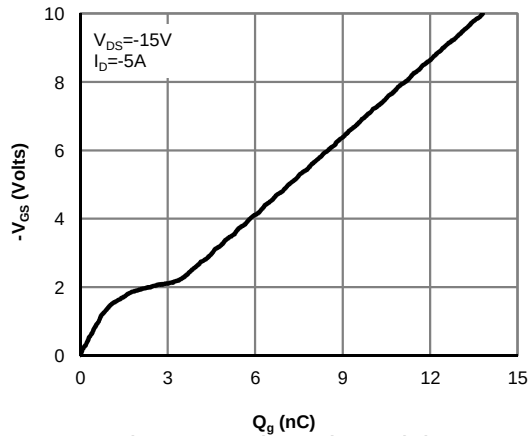


Figure 7: Gate-Charge Characteristics

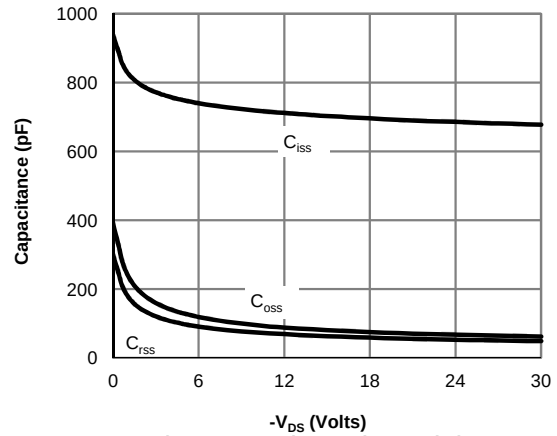


Figure 8: Capacitance Characteristics

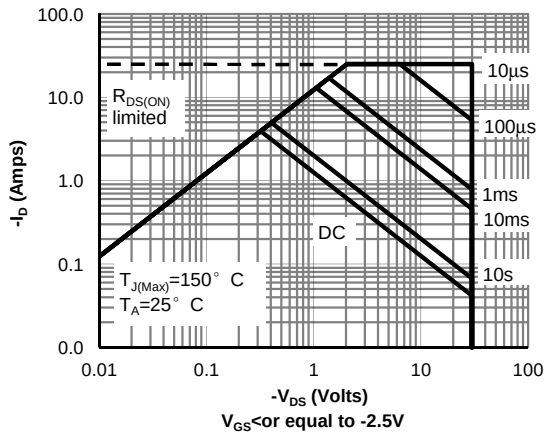


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

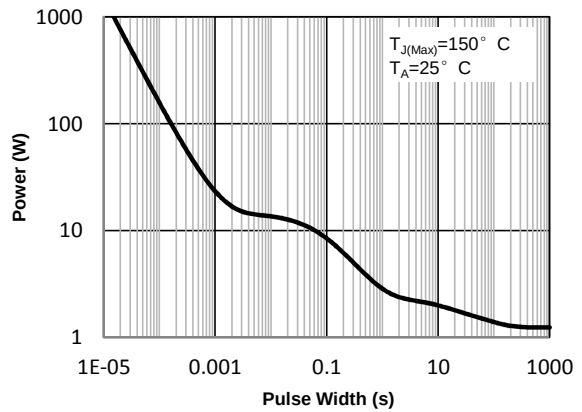


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note F)

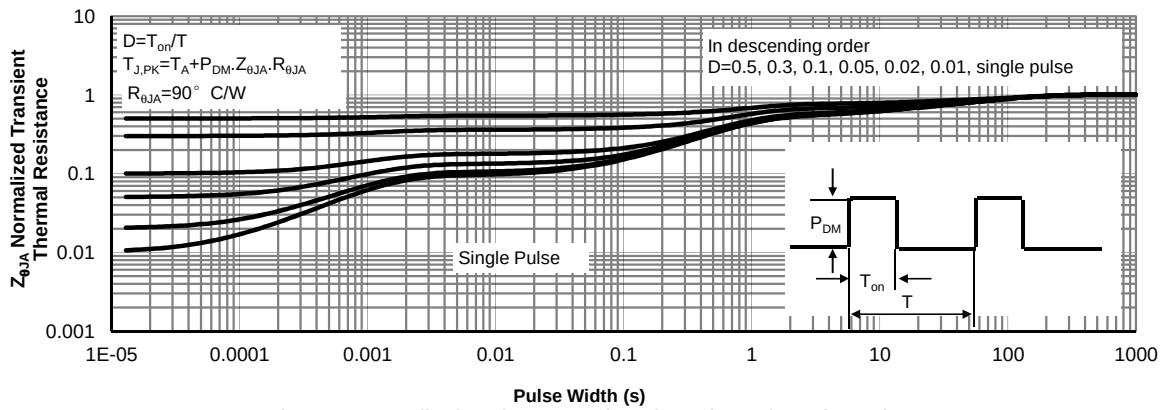
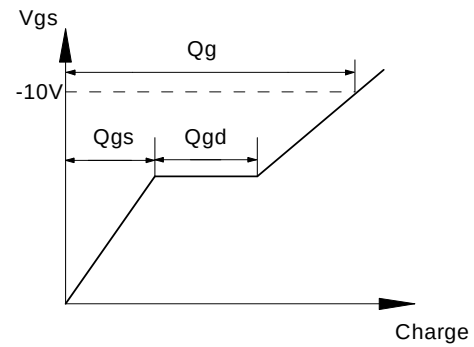
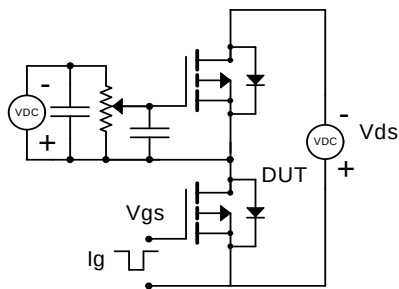
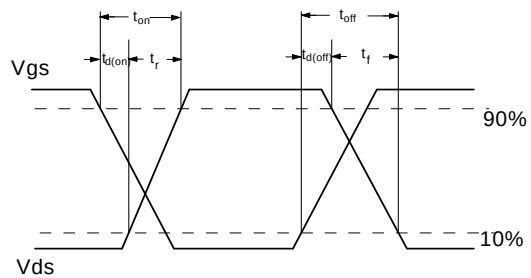
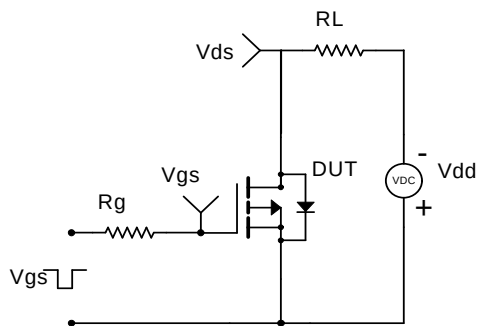


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

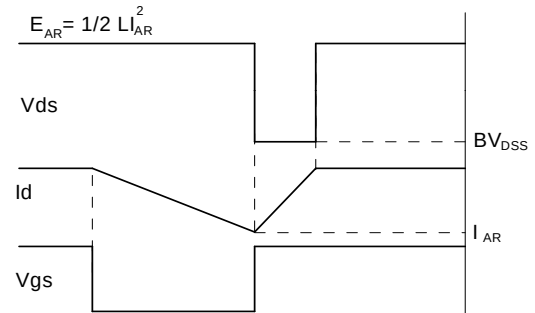
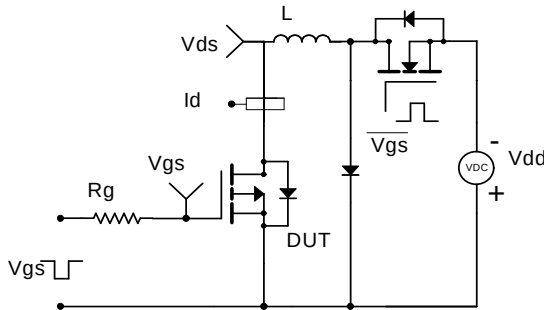
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

